

## HIGH-SIDE CURRENT SENSE AMPLIFIER

#### **Features**

- Complete, unidirectional high-side current sense capability
- 0.2% full-scale accuracy
- +5 to +36 V supply operation
- 85 dB power supply rejection
- 90 µA max supply current
- 9 µA shutdown current
- Operating Temperature Range: -40 to +85 °C
- 5-pin SOT-23 package
- RoHS-compliant

## **Applications**

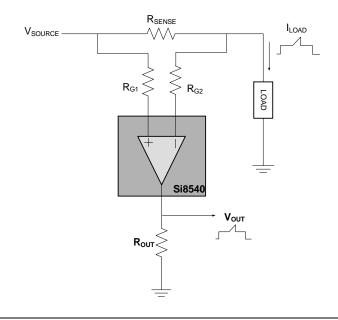
- Battery chargers
- Smart battery packs
- DC motor control

- Backup systems
- Current control applications

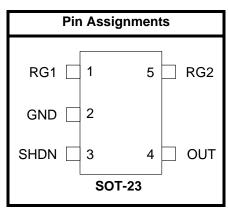
### **Description**

The Si8540 is a unidirectional, 36 V (max), high-side current sense amplifier for use in applications requiring current monitoring and/or control. This device draws bias current from the high-side line to which it is attached, eliminating the need for an external supply. It measures current from 0.1 to 10 A by sensing the voltage across an external sense resistor (or PCB trace) from dc to 20 kHz and can achieve measurement accuracies of 0.2% (typical) at full load. The device output is a current signal proportional to measured current and is easily converted to a scaled voltage using a single external resistor. The Si8540 is available in compact SOT-23 package.

### **Functional Block Diagram**







Patents pending



# TABLE OF CONTENTS

Section Sectio	<u>Page</u>
l. Electrical Specifications	4
2. Typical Application Schematic	6
B. Functional Description	7
3.1. Application Information	7
I. Typical Performance Data	9
5. Pin Descriptions	11
S. Ordering Guide	12
6.1. Device Marking	13
7. Package Outline: SOT-23	14
3. Land Pattern: SOT-23	15
Document Change List	16
Contact Information	18



## 1. Electrical Specifications

**Table 1. Absolute Maximum Ratings** 

Parameter	Value	Unit
Voltage at RG1, RG2, SHDN to GND	-0.3 to +40	V
Differential Input Voltage, RG1 to RG2	±0.3	V
Voltage at OUT	-0.3 to +8	V
Current into SHDN, GND, OUT, RG1, RG2	±50	mA
Continuous Power Dissipation ( $T_A = +70  ^{\circ}\text{C}$ ) 5-pin SOT23 derate 7.1 mW/ $^{\circ}$ C above +70 $^{\circ}$ C*	571	mW
Operating Temperature Range	-40 to +85	°C
Junction Temperature, T <sub>JMAX</sub>	Up to +150	°C

\*Note: The device is mounted on a standard PCB with a 100 mm<sup>2</sup> copper foil connected to the GND pin, no airflow. Permanent device damage may occur if the absolute maximum ratings are exceeded, and prolonged use at the absolute maximum ratings may affect reliability. It is recommended that the device operate within the limits indicated in Table 2, "DC and AC Characteristics".



Table 2. DC and AC Characteristics

(Unless otherwise specified:  $V_{RG1}$  = +5 to +36 V, RG1 = RG2 = 200,  $V_{SENSE}$  = 0 V,  $T_{A}$  = -40 to +85 °C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Operating Voltage	V <sub>RG1</sub>		5	_	36	V
Operating Frequency	F		0	20	_	kHz
Total Input Current	I <sub>RG1</sub> +I <sub>RG2</sub>	I <sub>LOAD</sub> = 0 A	_	46	90	μΑ
Input Currents	I <sub>RG1</sub> , I <sub>RG2</sub>	I <sub>LOAD</sub> = 0 A	_	23	45	μΑ
Input Current Matching	I <sub>OS</sub>	I <sub>RG1</sub> – I <sub>RG2</sub>	_	±0.4	±1.5	μΑ
Sense Voltage <sup>1</sup>	V <sub>SENSE</sub>		_	100	_	mV
OUT Current Accuracy	I <sub>RG</sub> /I <sub>OUT</sub>	V <sub>SENSE</sub> = 100 mV	_	±0.2	±1.5	%
No-Load OUT Error		V <sub>RG1</sub> = 10 V, V <sub>SENSE</sub> = 0 V	_	0.5	15	μΑ
Low-Level OUT Error		V <sub>RG1</sub> = 10 V, V <sub>SENSE</sub> = 3 mV	_	±0.5	<u>+</u> 10	μΑ
Power-Supply Rejection	PSR	V <sub>SENSE</sub> = 100 mV	_	-85	_	dB
Shutdown Supply Current	I <sub>RG1</sub> +I <sub>RG2</sub>	V <sub>SHDN</sub> = 2.4 V	_	3.5	9	μΑ
SHDN Input Low Voltage	V <sub>IL</sub>		_	_	0.3	V
SHDN Input Low Current	I <sub>IL</sub>	V <sub>SHDN</sub> = 0 V	_	_	1.0	μΑ
SHDN Input High Voltage	V <sub>IH</sub>		2.4	_	_	V
SHDN Input High Current	I <sub>IH</sub>	V <sub>SHDN</sub> = 2.4 V	_	_	1.0	μΑ
OUT Output Voltage Range	V <sub>OUT</sub>	V <sub>OUT</sub> clamped at 8 V	0	_	V <sub>RG1</sub> – 3.5 (<8)	V
OUT Output Resistance (Internal)		I <sub>OUT</sub> = 1.5 mA	1	3	_	ΜΩ
OUT Rise, Fall Time		$V_{SENSE} = 5 \text{ mV to } 150 \text{ mV},$ $R_{OUT} = 2 = k\Omega,$ $C_{OUT} = 50 \text{ pF, } 10\% \text{ to } 90\%$ (Note 2)		0.4 0.5	_	µs µs
OUT Settling Time to 1% of Final Value		$V_{SENSE}$ = 5 to 150 mV, $R_{OUT}$ = 2 k $\Omega$ , $C_{OUT}$ = 50 pF (Note 2)	_	1 2		µs µs
Maximum Output Current	I <sub>OUT</sub>	For I <sub>OUT</sub> > 1.5 mA the internal current limitation starts to limit the output current	1.5	_	10	mA

#### Notes:

- V<sub>SENSE</sub> is the voltage across the sense resistor.
   C<sub>OUT</sub> is the load capacitance seen by the OUT pin.



## 2. Typical Application Schematic

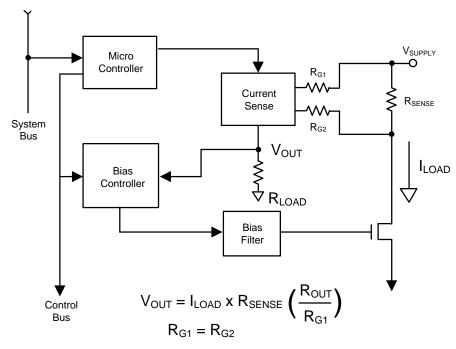


Figure 1. Connecting the Si8540 in a Power Control Application

## 3. Functional Description

The Si8540 is designed to operate over an input common-mode range of 5 to 36 V. Figure 2 shows an example Si8540 application with external sense resistor,  $R_{SENSE}$ , external current gain-setting resistors,  $R_{G1}$  and  $R_{G2}$ , and output scaling resistor,  $R_{OUT}$ . The supply current flowing into the Si8540 inverting and non-inverting inputs ( $R_{G1}$ ,  $R_{G2}$ ) is negligible compared to  $I_{LOAD}$  and, as a result, has no appreciable effect on measurement accuracy. The internal current sense amplifier measures the differential input voltage,  $V_{SENSE}$ , and generates an output current proportional to  $I_{LOAD}$ . Resistor  $R_{OUT}$  converts this current to a voltage, and its value determines the output signal gain. The Si8540 is placed in a low-power shutdown mode when SHDN is at  $V_{IH}$ .

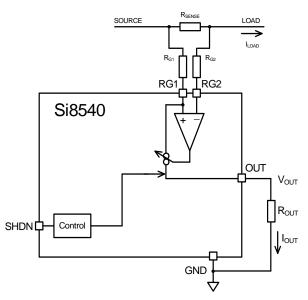


Figure 2. Si8540 Application Circuit

### 3.1. Application Information

The Si8540 can sense a wide range of currents with different sense resistor values. Table 3 lists typical operational values.

Full-scale Load Current	Current- Sense Resistor	Gain-Setting Resistors, RG1 = RG2 (Ω)	Output Resistor, R <sub>OUT</sub>	Full-Scale Output Voltage,	Scale Factor V <sub>OUT</sub> /I <sub>SENSE</sub>	and	l Error a 100% o ₋oad (%	f Full
I <sub>SENSE</sub> (A)	$R_{SENSE}$ (m $\Omega$ )		(kΩ)	V <sub>OUT</sub> (V)	(V/A)	1%	10%	100%
0.1	1000	200	5	2.5	25	10	1	0.2
1	100	200	5	2.5	2.5	10	1	0.2
5	20	100	2	2	0.4	5	1	0.2
10	5	50	2	2	0.2	5	1	0.4

Table 3. Recommended Current Sense Resistor for a Given Full-Scale Load Current



## 3.1.1. Selecting R<sub>SENSE</sub>

Selecting  $R_{SENSE}$  involves making the best trade-off between power efficiency and accuracy. Low  $R_{SENSE}$  values dissipate less power while higher values maximize accuracy. In general, it is best to choose a relatively high value for  $R_{SENSE}$  in applications where the measured current is small. For higher current applications, the sense resistor should be able to dissipate the heat from its power loss; otherwise, its value may drift or it may fail open, possibly causing a large differential voltage across RG1 and RG2 that may damage the device. In most applications,  $R_{SENSE}$  should have low inductance to reduce the impact of any high-frequency components in the current being measured (low inductance metal film resistors are recommended). Also, note that the Si8540 requires at least 3.5 V of voltage headroom between the voltage at pin RG1 and pin OUT. This voltage headroom decreases as  $R_{SENSE}$  increases. A good guideline for determining the maximum value for  $R_{SENSE}$  is shown in the following equation:

 $R_{SENSEmax} = (V_{SOURCE} - V_{OUTmax} - 3.5 V)/I_{LOAD}$ 

Where:

V<sub>SOURCE</sub> is the high-side voltage

V<sub>OUTmax</sub> is the full-scale output voltage at the OUT pin

 $I_{LOAD}$  is the current passing through  $R_{SENSE}$  measured by the Si8540

#### 3.1.2. Selecting RG1 and RG2

The values of resistors  $R_{G1}$  and  $R_{G2}$  determine the sense amp current-gain. These two resistors must have the same value, and resulting current gain is equal to  $R_{SENSE}$  /  $R_{G}$  (where  $R_{G} = R_{G1} = R_{G2}$ ).

The minimum value of  $R_G$  is determined by the maximum current at the OUT pin (1.5 mA) and by the resistance between the internal current sense amp input and the sense resistor (approximately 0.2  $\Omega$ ). As the value of  $R_G$  is reduced, the input resistance becomes a larger portion of the total gain-setting resistance. This gain error can be compensated by trimming  $R_G$  or  $R_{OUT}$ . A good guideline for determining the maximum value for  $R_G$  is shown in the following equation:

 $R_{Gmax} = (V_{SENSEmax} / 1.5 \text{ mA})$ 

Where:

R<sub>Gmax</sub> is the largest value for RG1 and RG2

 $V_{\mbox{\footnotesize SENSE}\mbox{\footnotesize max}}$  is the value of  $V_{\mbox{\footnotesize SENSE}}$  at maximum  $I_{\mbox{\footnotesize LOAD}}$ 

Note that for a given value of  $V_{SENSE}$ , a decrease of the  $R_G$  resistor values causes a corresponding increase in current at the OUT pin. This causes additional power to be dissipated in  $R_{OUT}$  rather than in the load, which can reduce efficiency. Note also that mismatches in the currents passing  $R_{G1}$  and  $R_{G2}$  (IOS) together with  $R_G$  affect the full scale error.

This error can be reduced by lowering the values of  $R_{G1}$ ,  $R_{G2}$  and/or lowering their tolerances. This error can also be reduced by increasing the value of  $R_{SENSE}$ .

### 3.1.3. Choosing R<sub>OUT</sub>

 $R_{OUT}$  must be chosen to generate the required full-scale output voltage at the full scale  $I_{OUT}$ , which, in turn, is determined by  $R_{G1}$ ,  $R_{G2}$ , and  $R_{SENSE}$ . The upper limit of  $R_{OUT}$  is determined by the input impedance of the device that it drives. This input impedance should be much larger than  $R_{OUT}$ ; otherwise, measurement accuracy will be degraded. A good guideline for choosing the value of  $R_{OUT}$  is shown in the following equation:

(V<sub>OUTfullscale</sub> x R<sub>G</sub>) / (I<sub>LOAD</sub> x R<sub>SENSE</sub>)



## 4. Typical Performance Data

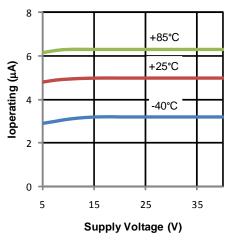


Figure 3. Supply Current vs. Supply Voltage

 $(R_{OUT}$  = 2 k $\Omega$ ,  $C_{OUT}$  = 50 pF,  $R_{G1}$  =  $R_{G2}$  = 200  $\Omega$ )

Figure 4. Transient Response 1

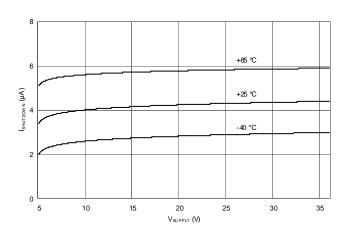


Figure 5. Shutdown Supply Current vs Supply Voltage



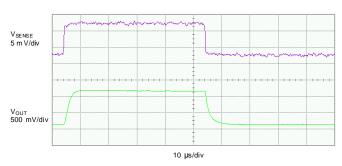


Figure 6. Transient Response 2

$$(R_{OUT} = 2~k\Omega,~C_{OUT} = 50~pF,~R_{G1} = R_{G2} = 200~\Omega,~V_{SENSE} = 100~mV)$$

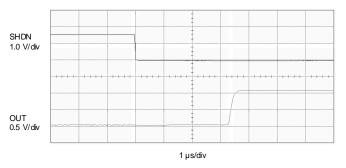


Figure 7. Startup Delay

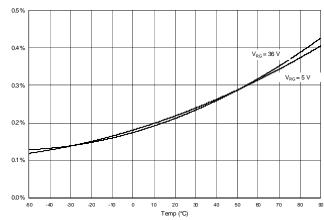
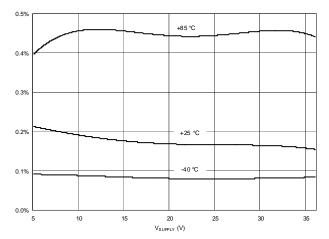


Figure 8. Output Error vs. Temperature







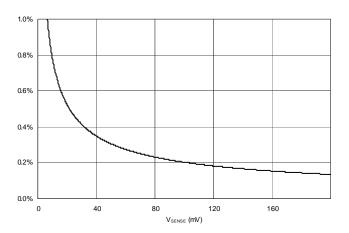


Figure 10. Output Error vs. Sense Voltage



# 5. Pin Descriptions

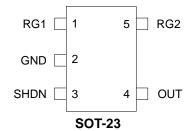


Figure 11. Pin Configuration

Table 4. Pin Descriptions

Pin Number	Name	Description		
	SOT23			
1	RG1	Power-side input.		
2	GND	Ground.		
3	SHDN	Shutdown input. Ground for normal operation. High voltage for shutdown.		
4	OUT	Current output.		
5	RG2	Load-side input.		



## 6. Ordering Guide

Ordering Part # <sup>1</sup>	Temperature Range	Package
Si8540-B-FW	−40 to +85 °C	SOT-23 <sup>2</sup>

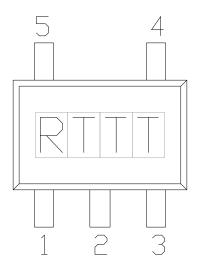
#### Notes:

- **1.** Tape and reel options are specified by adding an "R" suffix to the ordering part number. Example: "Si8450-B-FWR" indicates the SOT-23 package option in a tape and reel carrier.
- 2. Moisture sensitivity level (MSL) is (MSL2A) for SOT-23 package with peak reflow temperature of (260 °C) according to JEDEC industry-standard classifications.



## 6.1. Device Marking

## 6.1.1. SOT-23 Package Top Mark



## **6.1.2. Top Marking Explanation**

Line 1 Marking:	Manufacturing trace code	R = Device revision (B)
		TTT = Assembly trace code



## 7. Package Outline: SOT-23

Figure 12 illustrates the package details for the SOT-23. Table 5 lists the values for the dimensions shown in the illustration.

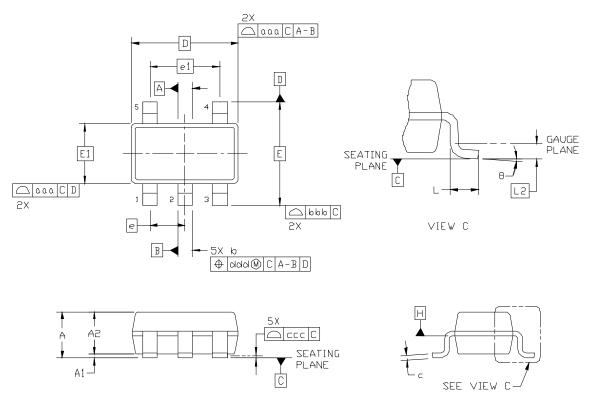


Figure 12. SOT-23 Package

**Table 5. SOT-23 Package Diagram Dimensions** 

Dimension	Min	Max	
А	_	1.45	
A1	0.00	0.15	
A2	0.90	1.30	
b	0.30	0.50	
С	0.08	0.20	
D	2.90 BSC		
Е	2.80 BSC		
E1	1.60 BSC		
е	0.95 BSC		

Dimension	Min	Max	
E1	1.90 BSC		
L	0.30	0.60	
L2	0.25	BSC	
θ	0°	8°	
aaa	0.	0.15	
bbb	0.20		
ccc	0.10		
ddd	0.20		

#### Notes:

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- 3. This drawing conforms to the JEDEC Solid State Outline MO-178, Variation AA.
- 4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020D specification for Small Body Components.

SILICON LARS

## 8. Land Pattern: SOT-23

Figure 13 illustrates the recommended land pattern details for the SOT-23 device. Table 6 lists the values for the dimensions shown in the illustration.

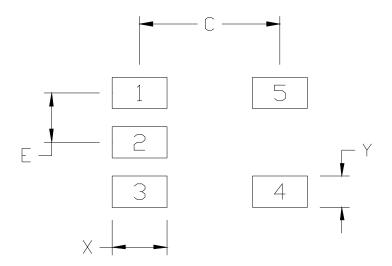


Figure 13. SOT-23 Land Pattern

**Table 6. SOT-23 Land Pattern Dimensions** 

Dimension	(mm)
С	2.70
E	0.95
X	1.05
Y	0.60

#### Notes:

#### General

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- 3. This Land Pattern Design is based on the IPC-7351 guidelines.
- **4.** All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

## **Card Assembly**

- **5.** A No-Clean, Type-3 solder paste is recommended.
- **6.** The recommended card reflow profile is per the JEDEC/IPC J-STD-020D specification for Small Body Components.



## **DOCUMENT CHANGE LIST**

# Revision 2.5 (July 2007 Integration Associates) to Revision 1.0 (March 2010 Silicon Laboratories)

- Reformatted document from IA2410 and renamed Si8540.
- Updated "Functional Block Diagram" on page 1.
- Updated " Description" on page 1.
- Updated Table 2 on page 5.
  - OUT current accuracy changed from ±1 to ±1.5%. (max)
  - No-Load OUT Error changed from 5 to 15 μA (max)
  - Low-Level OUT Error changed from ±5 to ±10 μA (max)
  - Temperature output error test conditions note updated to include temperature range of -40 to TBD° C.
- Updated "3. Functional Description" on page 7.
- Updated "3.1.1. Selecting R<sub>SENSE</sub>" on page 8.
- Updated "3.1.2. Selecting RG1 and RG2" on page 8.
- Updated "3.1.3. Choosing R<sub>OUT</sub>" on page 8.
- Removed temperature sensing function throughout.
- Added recommended PCB Land Pattern sections.
- Reformatted document from "IA2410 Rev 2.5" (Integration Associates) and renamed and rereleased as "Si8540 Rev 1.0" (which obsoletes the previous preliminary internal revision 2.6).

#### **Revision 1.0 to Revision 1.1**

- MSL for the SOT-23 package improved to MSL2A (see "6. Ordering Guide" on page 12).
- Added "6.1. Device Marking" on page 13.

#### **Revision 1.1 to Revision 1.2**

■ Removed SOIC-8 package throughout document.



Notes:



## Si8540

## **CONTACT INFORMATION**

Silicon Laboratories Inc.

400 West Cesar Chavez Austin, TX 78701 Tel: 1+(512) 416-8500

Fax: 1+(512) 416-9669 Toll Free: 1+(877) 444-3032

Please visit the Silicon Labs Technical Support web page: https://www.silabs.com/support/pages/contacttechnicalsupport.aspx and register to submit a technical support request.

#### **Patent Notice**

Silicon Labs invests in research and development to help our customers differentiate in the market with innovative low-power, small size, analog-intensive mixed-signal solutions. Silicon Labs' extensive patent portfolio is a testament to our unique approach and world-class engineering team.

The information in this document is believed to be accurate in all respects at the time of publication but is subject to change without notice. Silicon Laboratories assumes no responsibility for errors and omissions, and disclaims responsibility for any consequences resulting from the use of information included herein. Additionally, Silicon Laboratories assumes no responsibility for the functioning of undescribed features or parameters. Silicon Laboratories reserves the right to make changes without further notice. Silicon Laboratories makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Silicon Laboratories assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. Silicon Laboratories products are not designed, intended, or authorized for use in applications intended to support or sustain life, or for any other application in which the failure of the Silicon Laboratories product could create a situation where personal injury or death may occur. Should Buyer purchase or use Silicon Laboratories products for any such unintended or unauthorized application, Buyer shall indemnify and hold Silicon Laboratories harmless against all claims and damages.

Silicon Laboratories and Silicon Labs are trademarks of Silicon Laboratories Inc.

Other products or brandnames mentioned herein are trademarks or registered trademarks of their respective holders.



# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Silicon Laboratories:

SI8540-B-FSR SI8540-B-FWR